

What is claimed is:

1. A crosstalk cancellation circuit for suppressing crosstalk noise of interconnections in an integrated circuit, comprising:

5 N (N is an even number of 2 or more) number of first inverters;

a first interconnection for connecting the N number of first inverters in series;

N number of second inverters; and

10 a second interconnection for connecting said N number of second inverters in series, and

wherein said first and second interconnections are arranged adjacent in parallel or substantially parallel to each other,

15 wherein at least one first inverters among said N number of first inverters is arranged at a location where crosstalk noise due to a parasitic capacity between said first and second interconnections is canceled out or substantially canceled out on said
20 second interconnection, and

wherein at least one second inverter among said N number of second inverters is arranged at a location where crosstalk noise due to a parasitic capacity between said first and second interconnections
25 is canceled out or substantially canceled out on said

first interconnection.

2. A crosstalk cancellation circuit as set forth in claim 1, wherein

said N number of first inverters are arranged
5 in the approximately same interval in said first interconnection, and

said N number of second inverters are arranged in said second interconnection at the middle positions where distances from the adjacent first
10 inverters are equal.

3. A crosstalk cancellation circuit as set forth in claim 1, wherein,

in each of said N number of first inverters, a time when an input signal voltage of the related first inverter changes and a time when an output signal voltage
15 changes overlap, and

in each of said N number of second inverters, a time when the input signal voltage of the related second inverter changes and a time when the output signal
20 voltage changes overlap.

4. A crosstalk cancellation circuit as set forth in claim 1, wherein said N number of first and second inverters and said first and second interconnections comprise buses in said integrated circuit.

6. An interconnection module in an integrated circuit, comprising:

input lines of said M number of inverters;
output lines of said M number inverters; and
L number of signal lines, and

7. An interconnection module as set forth in claim 6, wherein

8. An interconnection module as set forth in claim 6, wherein said integrated circuit is configured as

a semiconductor integrated circuit manufactured by a process rule of less than 0.25 micrometer.

9. A method of interconnection of an automatic interconnection apparatus for laying out interconnections in an integrated circuit, comprising the steps of:

a first step of arranging a plurality of interconnections parallel or substantially parallel; and

a second step of inserting the same number of inverters at said plurality of interconnections, and

wherein said second step having a third step of inserting each inverter at a location where crosstalk noise due to a parasitic capacity of the adjoining interconnections is canceled out or substantially canceled out on the related adjoining interconnections.

10. A method of interconnection of an automatic interconnection apparatus as set forth in claim 9, wherein, in said third step, said inverters are inserted at alternate locations with respect to the interconnections adjoining each other among said plurality of interconnections.

11. A method of interconnection of an automatic interconnection apparatus as set forth in claim 9, wherein, in said third step, each inverter is inserted at one interconnection between interconnections adjoining each other at a location where the distance from the

inverter of the other interconnection becomes the maximum or in the vicinity of that location.

12. A method of interconnection of an automatic interconnection apparatus as set forth in claim 9,
5 wherein a time when an input signal voltage changes and a time when an output signal voltage changes overlap.

13. A method of interconnection of an automatic interconnection apparatus as set forth in claim 9,
wherein said interconnections are interconnections of
10 buses.

14. A method of interconnection of an automatic interconnection apparatus as set forth in claim 9,
wherein said integrated circuit is configured as a semiconductor integrated circuit manufactured by a
15 process rule of less than 0.25 micrometer.

15. A method of interconnection of an automatic interconnection apparatus as set forth in claim 9,
wherein the inverters inserted at said plurality of interconnections are inverters having the same
20 configuration.

16. An integrated circuit comprising
a crosstalk cancellation circuit for
suppressing crosstalk noise of interconnections in an integrated circuit, and
25 wherein said crosstalk cancellation circuit

comprises

N (N is an even number of 2 or more)
number of first inverters,

a first interconnection for connecting
5 the N number of first inverters in series, N number of
second inverters, and

a second interconnection for connecting
said N number of second inverters in series, and

Wherein said first and second
10 interconnections are arranged adjacent in parallel or
substantially parallel to each other,

wherein at least one first inverters
among said N number of first inverters is arranged at a
location where crosstalk noise due to a parasitic
15 capacity between said first and second interconnections
is canceled out or substantially canceled out on said
second interconnection, and

wherein at least one second inverter
among said N number of second inverters is arranged at a
20 location where crosstalk noise due to a parasitic
capacity between said first and second interconnections
is canceled out or substantially canceled out on said
first interconnection.